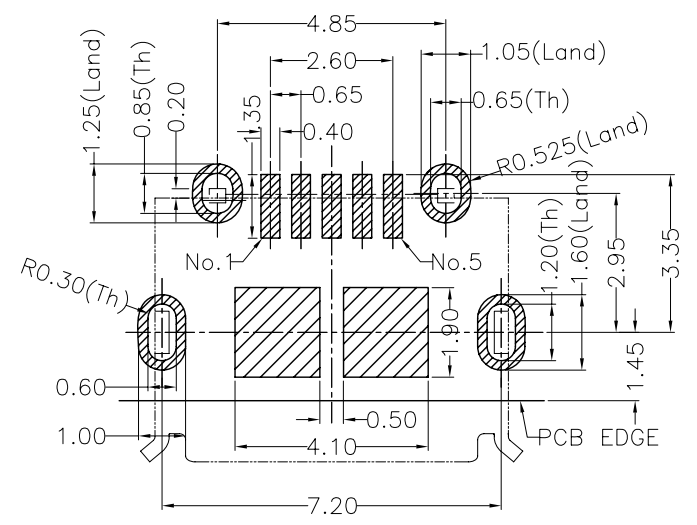
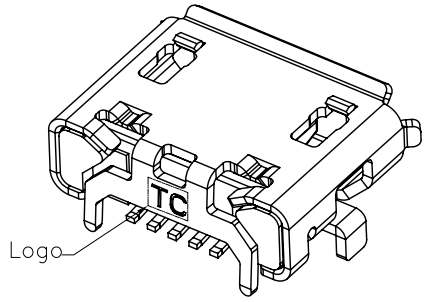
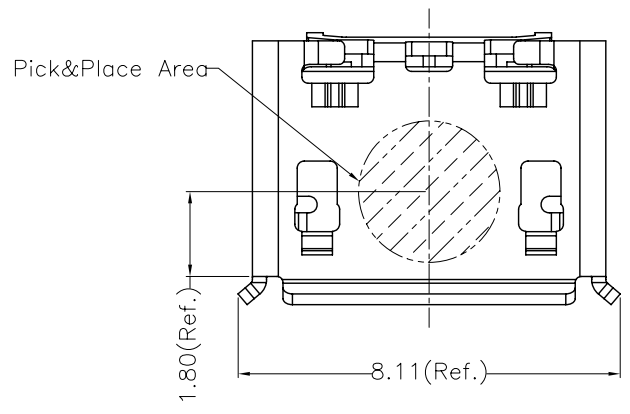


1 2 3 4 5 6 7 8 9 10

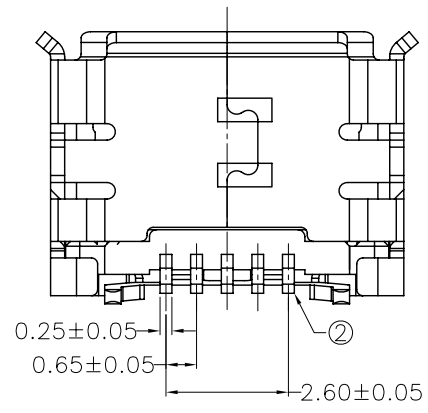
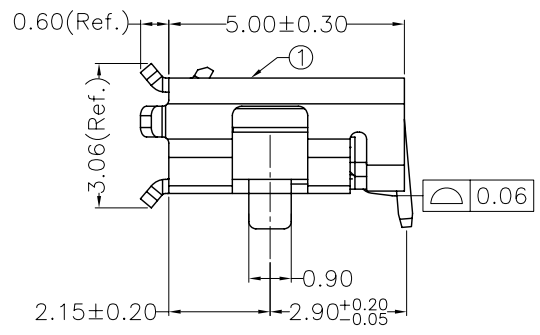
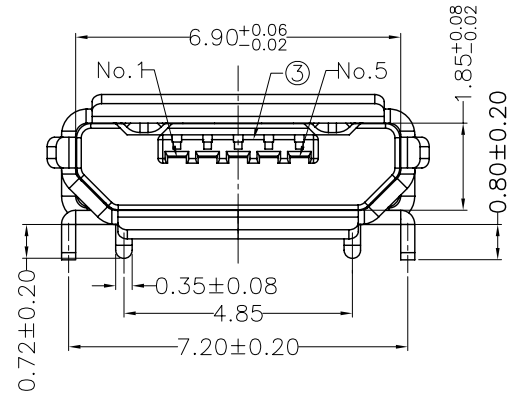
THE PART MEETS TECONN "GP001" COMPLIANCE

A  
B  
C  
D  
E  
F

A  
B  
C  
D  
E  
F



Recommended PCB Layout  
(General Tolerance:±0.05)




A4A0507 - X - XX - R  
 LOGO&Shell Plating E:With "TC" LOGO F:Without LOGO  
 Mating Area plating  
 01: Au 1u"Min.  
 03: Au 3u"Min.  
 05: Au 5u"Min.  
 10: Au 10u"Min.  
 15: Au 15u"Min.  
 30: Au 30u"Min.

Item	Title	Material	Dispose	Remark
1	Shell	Stainless Steel	Matte Tin 50u"(min).	t=0.30
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:G/F	t=0.15
3	InsertMolding	LCP	UL94V-0	Black

- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:  
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

A	TE2011-xxxx	New Drawing	2011/11/03
REV	ECN NO	DESCRIPTION	DATE

X. ± 0.35	APPD:	TITLE:	 泰康电子 TECONN
.X ± 0.25	CHKD:	Micro B Rec./Shell Dip	
.XX ± 0.15	DR: Kevin Han	PART NO: A4A0507-E(F)-XX-R	
.XXX ± 0.10		DWG NO: C-A4A0507-E(F)-XX-R	
X* ± 2*		UNITS: mm	CUSTOMER DRAWING SHEET:10F1 REV: A
.X* ± 1.5*		SCALE: 6 : 1	

1 2 3 4 5 6 7 8 9 10